

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YOSHINAO OGATA	06/30/2014
	MASATAKA KATO	06/30/2014
	MASAYA UYAMA	06/30/2014
RECEIVING PARTY DATA		
Name:	Canon Kabushiki Kaisha	
Street Address:	30-2, Shimomaruko 3-Chome, Ohta-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	146-8501	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14322235	
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ATTORNEY DOCKET NUMBER:	10118685US01	
NAME OF SUBMITTER:	CHIAKI SUZUKI	
SIGNATURE:	/CHIAKI SUZUKI/	
DATE SIGNED:	11/30/2014	
Total Attachments: 2		
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source=10118685US01Assignment#page2.tif		

ASSIGNMENT

FOR VALUE RECEIVED, I/WE

Yoshinao OgataMasataka KatoMasaya Uyamahereby sell, assign, transfer and convey unto **CANON KABUSHIKI KAISHA**

a corporation of Japan

having a place of business at 30-2, Shimomaruko 3-chome, Ohta-ku, Tokyo, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title, and interest, for all countries, in and to certain inventions relating to

METHOD OF ETCHING A SILICON SUBSTRATE

and described in an application for Letters Patent of the United States executed by me/us, and
 filed on _____ as United States Application No. _____ or
 as PCT International Application No. _____

and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues and extensions thereof, and all applications for Letters Patent or other grants of protection of proprietary rights including, but not limited to, inventor's certificate, utility model, utility certificate, patent of importation, registration of patent and industrial design registration which may be filed, and which may be granted, upon said inventions in any countries or regions foreign to the United States, and all reissues, renewals and extensions thereof; and I/we hereby authorize and request the Commissioner for Patents and Trademarks of the United States, and all officials of countries or regions foreign to the United States having authority to do so, to issue all such Letters Patent or other grants of protection upon said inventions to the Assignee or to such nominees as it may designate.

AND I/we authorize and empower the said Assignee or nominees to invoke and claim for any application for such Letters Patent or other grants of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by a convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from me/us.

AND I/we hereby consent that a copy of this assignment shall be deemed a full and formal equivalent of any assignment, consent to file or like document which may be required in any country or region for any purpose and

more particularly in proof of the right of the said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND I/we hereby covenant that I/we have the full right to convey the entire right, title and interest herein assigned and that I/we have not executed and will not execute any agreement in conflict herewith.

AND I/we hereby covenant and agree that I/we will communicate to said Assignee or nominees all facts known to me/us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining, and enforcing all lawful patent or other grants of protection of said inventions in any and all countries and regions.

By: Yoshinao Ogata
Yoshinao Ogata

Date: June 30, 2014

By: Masataka Kato
Masataka Kato

Date: June 30, 2014

By: Masaya Uyama
Masaya Uyama

Date: June 30, 2014

By: _____

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